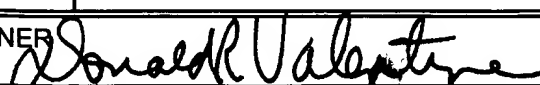


INFORMATION DISCLOSURE CITATION PTO-1449				ATTY. DOCKET NO. A-68779/REB/VEJ		SERIAL NO. 09/174,337	
				APPLICANT Jorné et al.			
				FILING DATE October 19, 1998		GROUP 1741	
U.S. PATENT DOCUMENTS							
EXAMINER'S INITIALS	PATENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE	
DEV	5,230,743	07/27/93	Thompson et al.	134	32	07/30/92	
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FOREIGN PATENT DOCUMENTS							
EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation Yes <input type="checkbox"/> No <input type="checkbox"/>	
OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)							
DEV	J. Jorné, Current Distribution of Copper Electroplating on Wafers, Report, Cupricon, Inc., Rochester, NY (July 24, 1997)						
DEV	H.S. Rathole and D. Nguyen, Copper Metallization for Sub-Micron Technology in Advance Metallization Processes, VLSI Multilevel Interconnection, Santa Clara, CA, June 9, 1997						
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DEV	VLSI Multilevel Interconnection Conference, VMCI, Santa Clara, CA, June 10-12, 1997						
EXAMINER				DATE CONSIDERED 4-25-00			

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

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